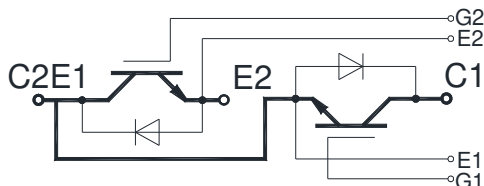




## MRI 450.12-E

### 2 in 1 IGBT Modules



#### Features:

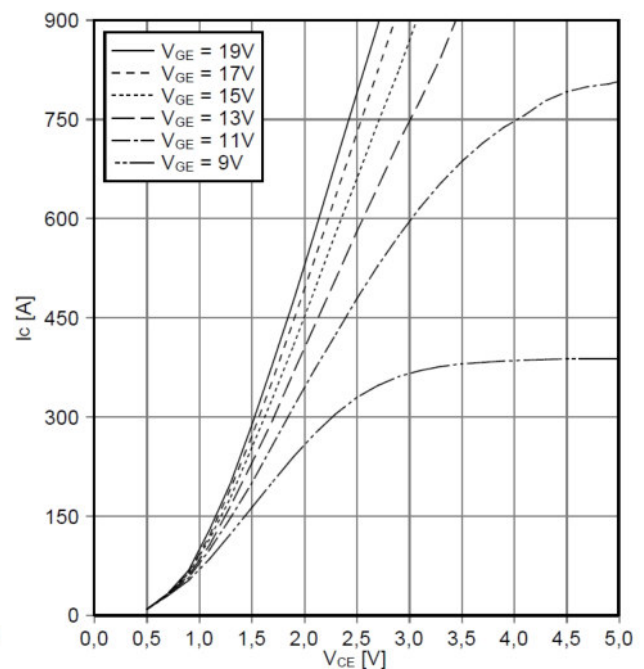
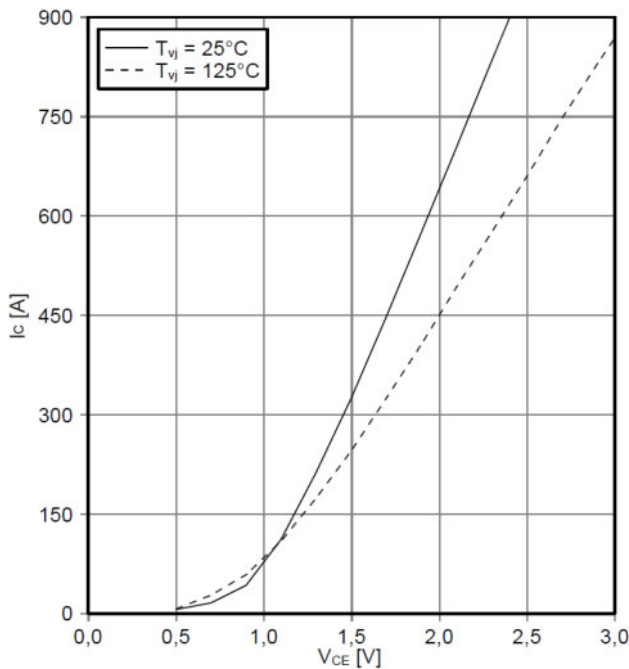
- Low  $V_{CEsat}$
- Standard Housing

#### Typical Applications:

- Motor Drive
- Servo Drive
- Uninterruptible Power Supply System
- Wind Turbines
- High Power Converters

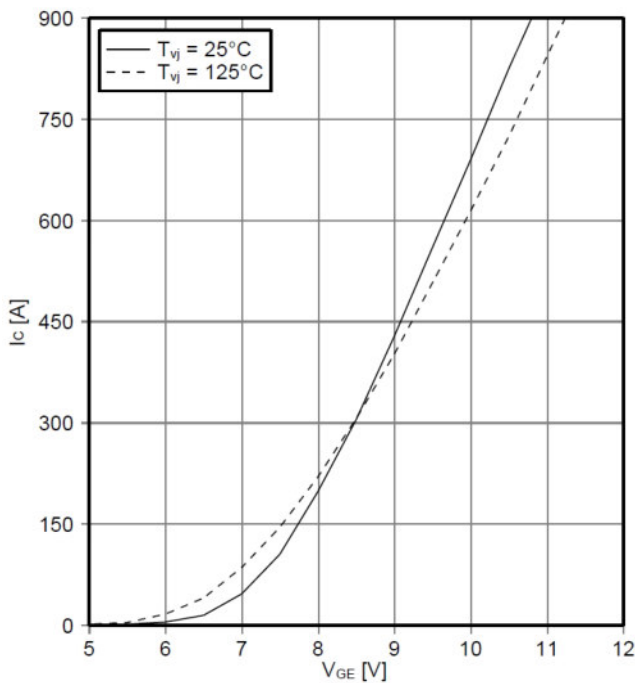
SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT	
			Min	Type	Max		
$V_{CES}$	Collector-Emitter voltage	$T_j=25^\circ\text{C}$			1200	V	
$V_{GES}$	Gate-Emitter voltage	$T_j=25^\circ\text{C}$			$\pm 20$	V	
$I_c$	Collector current	Continuous@ $T_C=80^\circ\text{C}$			450	A	
$I_{CP}$		$T_P=1\text{ms}$			900	A	
$P_c$	Collector power dissipation	$T_j=25^\circ\text{C}$ , 1 device			2100	W	
$T_{Vjop}$	Junction temperature	/	-40		125	$^\circ\text{C}$	
$T_{stg}$	Storage temperature	/	-40		125	$^\circ\text{C}$	
$V_{iso}$	Isolation between terminal and copper base	$T_j=25^\circ\text{C}$ , AC: 1minute	2500			V	
Screw torque	Mounting(M5)	/	3.0		6.0	N·m	
	Terminals(M6)	/	3.0		6.0	N·m	
$I_{CES}$	Zero gate voltage collector current	$T_j=25^\circ\text{C}$ , $V_{CE}=1200\text{V}$ , $V_{GE}=0\text{V}$			5.0	mA	
$I_{GES}$	Gate-Emitter leakage current	$T_j=25^\circ\text{C}$ , $V_{CE}=0\text{V}$ , $V_{GE}=\pm 20\text{V}$			0.4	$\mu\text{A}$	
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j=25^\circ\text{C}$ , $V_{CE}=20\text{V}$ , $I_c=18\text{mA}$	5.0	5.8	6.5	V	
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_c=450\text{A}$		1.70	2.15	V	
		$T_j=125^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_c=450\text{A}$		2.00		V	
$R_{Gint}$	Internal gate resistor	$T_j=25^\circ\text{C}$		1.7		$\Omega$	
$C_{ies}$	Input capacitance	$T_j=25^\circ\text{C}$ , $V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$		32.0		nF	
$C_{res}$	Reverse transfer capacitance			1.5		nF	
$t_{on}$	Turn-on time	$V_{CC}=600\text{V}$ , $I_c=450\text{A}$ , $V_{GE}=\pm 15\text{V}$ , $R_g=1.6\Omega$ , Inductive load	$T_j=25^\circ\text{C}$		250		ns
			$T_j=125^\circ\text{C}$		300		ns
$t_r$	Rise time		$T_j=25^\circ\text{C}$		90		ns
			$T_j=125^\circ\text{C}$		100		ns
$t_{off}$	Turn-off time		$T_j=25^\circ\text{C}$		550		ns
			$T_j=125^\circ\text{C}$		650		ns
$t_f$	Fall time		$T_j=25^\circ\text{C}$		130		ns
			$T_j=125^\circ\text{C}$		160		ns
$E_{on}$	Turn-on energy loss per pulse	$T_j=25^\circ\text{C}$		22		mJ	
		$T_j=125^\circ\text{C}$		33		mJ	
$E_{off}$	Turn-off energy loss per pulse	$T_j=25^\circ\text{C}$		43		mJ	
		$T_j=125^\circ\text{C}$		65		mJ	
$I_{sc}$	Short circuit	$T_j=125^\circ\text{C}$ , $V_{CC}=900\text{V}$ , $V_{GE}\leq 15\text{V}$		1800		A	
$V_F$	Forward on voltage	$I_F=450\text{A}$ , $T_j=25^\circ\text{C}$		1.65	2.15	V	
		$I_F=450\text{A}$ , $T_j=125^\circ\text{C}$		1.65		V	
$t_{rr}$	Reverse recovery time	$I_F=450\text{A}$ , $T_j=25^\circ\text{C}$		150		$\mu\text{s}$	

$t_{rr}$	Reverse recovery time	$I_F=450A$	$T_J=125^{\circ}C$	210	$\mu s$
$R_{th(j-c)}$	Thermal resistance(1 device)	IGBT		0.06	$^{\circ}C/W$
		FWD		0.10	$^{\circ}C/W$
$R_{th(c-H)}$	Thermal resistance, case to heatsink	per module		0.009	$^{\circ}C/W$
		IGBT		0.030	$^{\circ}C/W$
		FWD		0.050	$^{\circ}C/W$
$R_{25}$	Rated resistance	$T_C=25^{\circ}C$		5.0	$k\Omega$
$\Delta R/R$	Deviation of R100	$T_C=100^{\circ}C, R_{100}=493 W$		-5	5 %
$P_{25}$	Power dissipation	$T_C=25^{\circ}C$		20	mW
$B_{25/50}$	B-value	$R_2=R_{25}exp [B_{25/50}(1/T_2-1/(298,15 K))]$		3375	K
$B_{25/80}$	B-value	$R_2=R_{25}exp [B_{25/80}(1/T_2-1/(298,15 K))]$		3411	K
$B_{25/100}$	B-value	$R_2=R_{25}exp [B_{25/100}(1/T_2-1/(298,15 K))]$		3433	K
$L_{sCE}$	Stray inductance module			20	nH
$R_{CC+EE}$	Module lead resistance, terminals - chip	$T_C=25^{\circ}C$ , per switch		1.10	$m\Omega$
$W_t$	Weight			345	g
Outline	465H3				

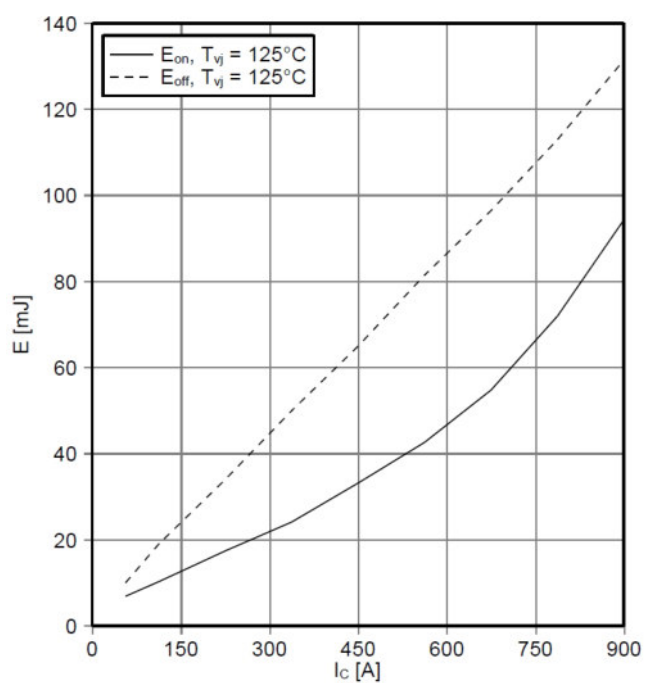


output characteristic IGBT, Inverter (typical)

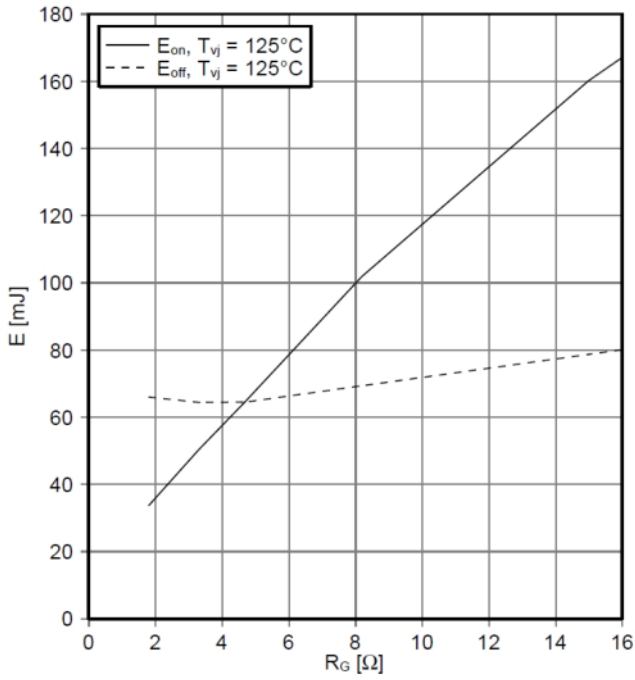
output characteristic IGBT, Inverter (typical)



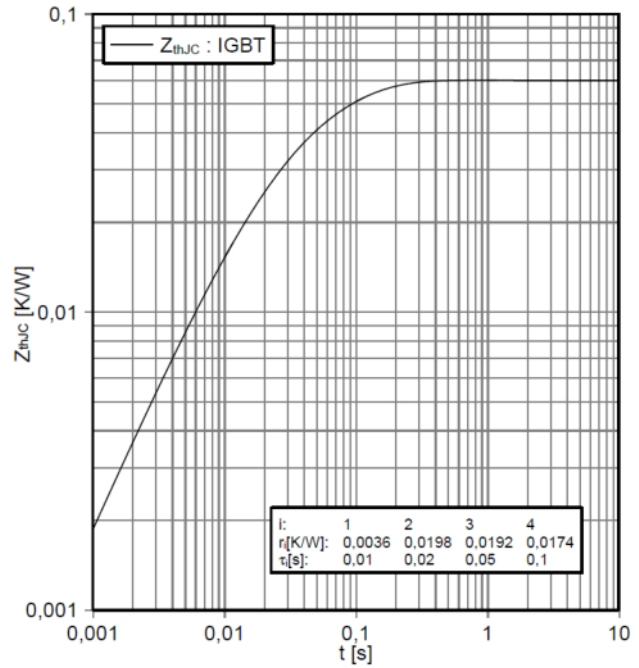
transfer characteristic IGBT, Inverter (typical)



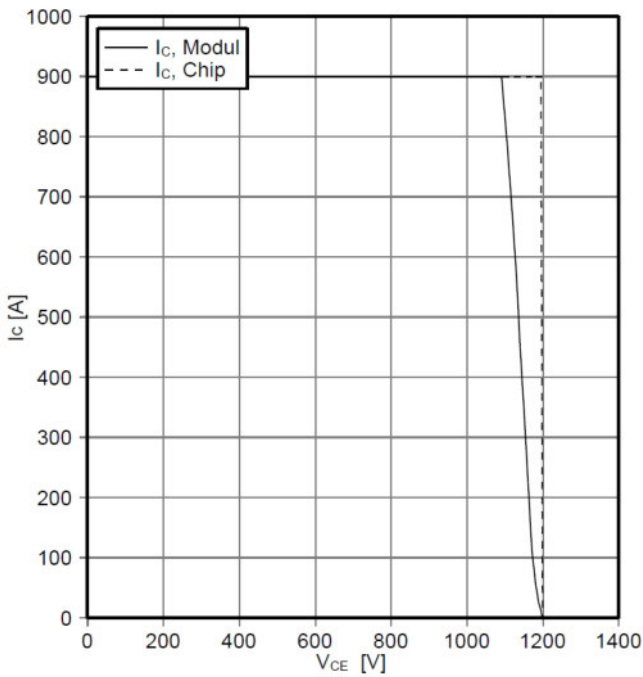
switching losses IGBT, Inverter (typical)



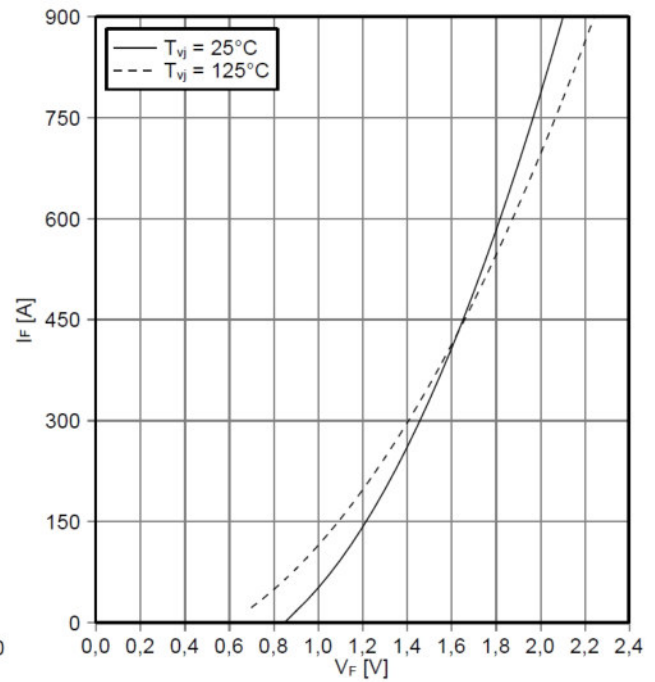
switching losses IGBT, Inverter (typical)



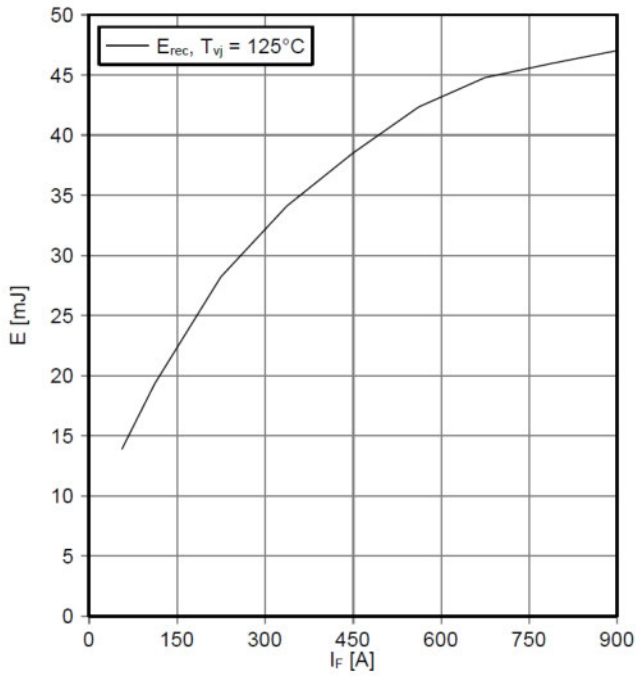
transient thermal impedance IGBT, Inverter



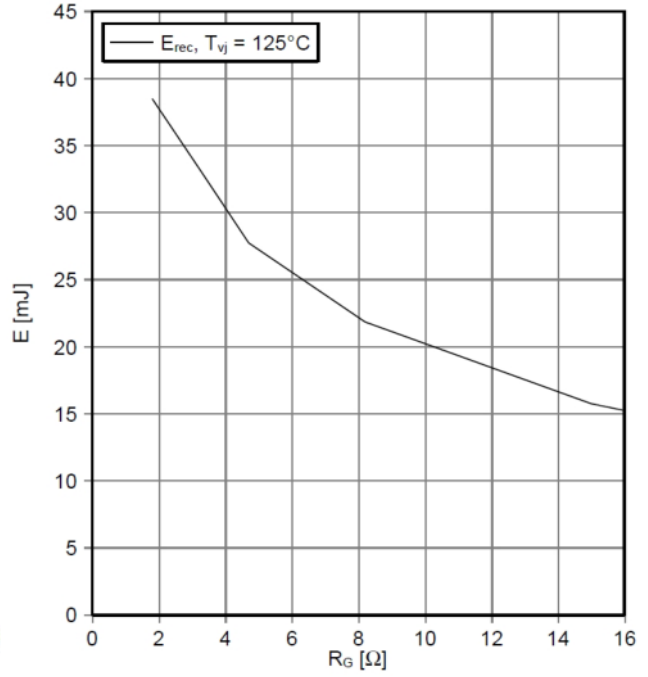
reverse bias safe operating area IGBT, Inverter (RBSOA)



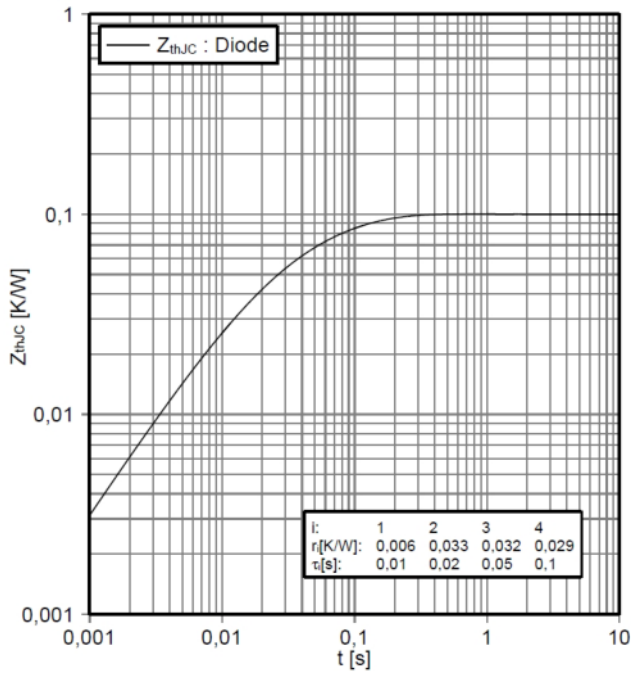
forward characteristic of Diode, Inverter (typical)



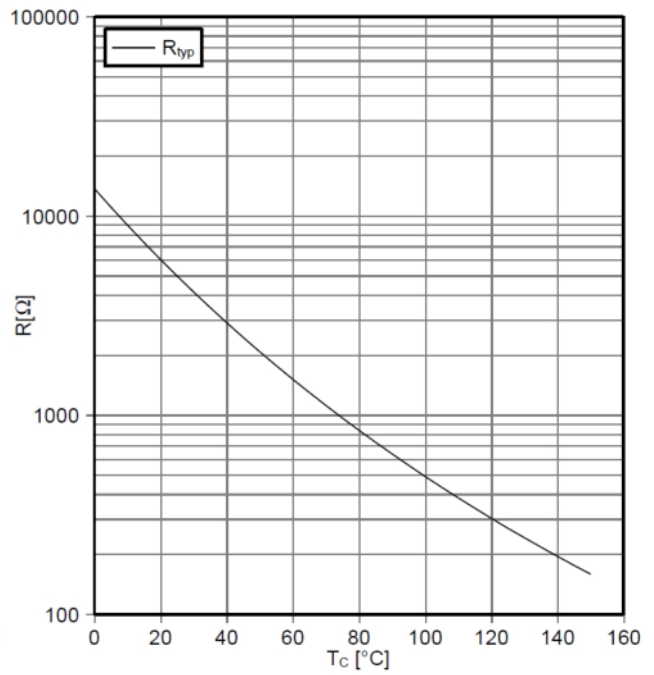
switching losses Diode, Inverter (typical)



switching losses Diode, Inverter (typical)



transient thermal impedance Diode, Inverter



NTC-Thermistor-temperature characteristic (typical)

**Outline:**

